

I. Amendments to the Claims

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of the Claims

Please cancel claims 15 through 19.

Please amend claims 1-3, 7-9 and 12-14, and cancel claims 15 through 19, as follows:

1. (currently amended) ~~A single light emitting diode package comprising:
a standalone ceramic cavity comprising a ceramic substrate for mounting
a light emitting diode in a single cavity and substantially vertical ceramic
sidewalls for minimizing light leakage; and
a metallic coating on a portion of said ceramic substrate and a portion of said
ceramic sidewalls for reflecting light in a predetermined direction.~~

A standalone light emitting diode package, comprising:

a housing comprising substantially vertical sidewalls and a substrate, the
sidewalls and the substrate defining a cavity having a bottom, the substrate
being located at the bottom of the cavity, portions of the substrate engaging or
being adjacent to the vertical sidewalls, the substantially vertical sidewalls and
the substrate being formed of ceramic;

at least one light-reflective metallic coating disposed over at least
portions of the sidewalls and the substrate;

a light emitting diode mounted on or in the substrate, and
an optically transparent material disposed in the cavity and covering the light
emitting diode;

wherein the ceramic composition of the sidewalls and the substrate and the
light-reflective coating cooperate to minimize light leakage through or into the

housing when the light emitting diode is energized, the metallic coating reflects light incident thereon in a predetermined direction, and the optically transparent material protects the light emitting diode.

2. (currently amended) The light emitting diode package of Claim 1 wherein said ~~ceramic~~-cavity is filled with an optically transparent material.
3. (currently amended) The light emitting diode package of Claim 1 wherein said ~~ceramic~~-cavity is substantially white in color.
4. (original) The light emitting diode package of Claim 1 wherein said metallic coating comprises silver.
5. (original) The light emitting diode package of Claim 1 wherein said metallic coating comprises gold.
6. (original) The light emitting diode package of Claim 1 wherein said metallic coating is formed by plating.
7. (currently amended) The light emitting diode package of Claim 1 wherein said ~~ceramic~~-cavity is formed to contain a plurality of light emitting diodes.
8. (currently amended) ~~A method for manufacture of a light emitting diode package comprising:~~

~~forming a single ceramic cavity comprising a ceramic substrate for mounting a light emitting diode in a single cavity and substantially vertical ceramic sidewalls for reducing light leakage;~~
~~coating a portion of said ceramic substrate with a light reflective material;~~
~~positioning a light emitting diode on said substrate; and~~
~~depositing an optically transparent material in said cavity to protect said light emitting diode.~~

A method of making a standalone light emitting diode package, the package comprising a housing having substantially vertical sidewalls and a substrate, the sidewalls and the substrate defining a cavity having a bottom, the substrate being located at the bottom of the cavity, portions of the substrate engaging or being adjacent to the vertical sidewalls, the substantially vertical sidewalls and the substrate being formed of ceramic, at least one light-reflective metallic coating being disposed over at least portions of the sidewalls and the substrate, a light emitting diode being mounted on or in the substrate, an optically transparent material being disposed in the cavity and covering the light emitting diode, the ceramic composition of the sidewalls and the substrate and the light-reflective coating cooperating to minimize light leakage through or into the housing when the light emitting diode is energized, the metallic coating reflecting light incident thereon in a predetermined direction, and the optically transparent material protecting the light emitting diode, the method comprising:

- (a) providing the housing;
- (b) coating the at least portions of the sidewalls and substrate with the at least one light-reflective metallic coating;
- (c) mounting the light emitting diode on or in the substrate, and
- (d) depositing the optically transparent material in the cavity.

9. (currently amended) The method as described in Claim 8 wherein said ~~ceramic cavity~~ is substantially white in color.

10. (original) The method as described in Claim 8 wherein said light reflective material comprises silver.

11. (original) The method as described in Claim 8 wherein said light reflective material comprises gold.

12. (original) The method as described in Claim 8 wherein said reflective coating is formed using plating.

13. (currently amended) The method as described in Claim 8 wherein said ~~ceramic~~ cavity is formed to mount a plurality of light emitting diodes therein.

14. (currently amended) ~~A light source comprising:~~
~~a single ceramic cavity comprising a ceramic substrate for mounting a light~~
~~emitting diode in said single cavity and substantially vertical ceramic sidewalls~~
~~for reducing light leakage;~~
~~a metallic coating on a portion of said ceramic substrate for reflecting light in a~~
~~predetermined direction;~~
~~a light emitting diode coupled to said substrate; and~~
The method as described in Claim 8 further comprising depositing epoxy as
the optically transparent material in the cavity.

15. (cancelled) The light source of Claim 14 wherein said ceramic cavity is substantially white in color.

16. (cancelled) The light source of Claim 14 wherein said metallic coating comprises silver.

17. (cancelled) The light source of Claim 14 wherein said metallic coating comprises gold.

18. (cancelled) The light source of Claim 14 wherein said metallic coating is formed by plating.

19. (cancelled) The light source of Claim 14 further comprising a plurality of light emitting diodes coupled to said substrate.